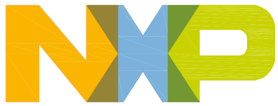

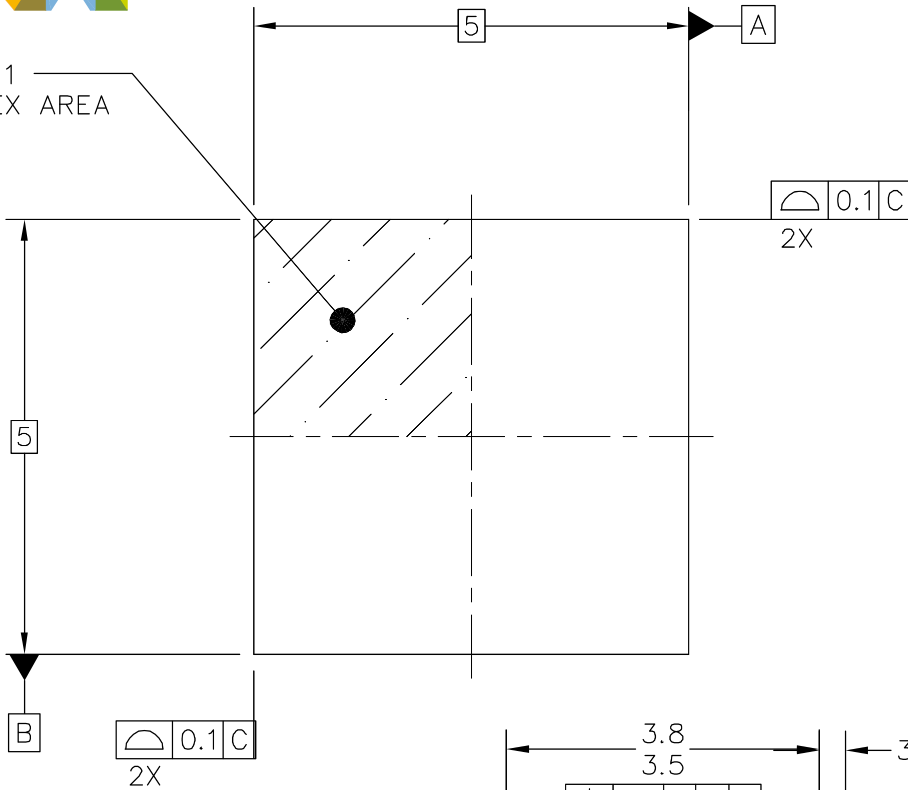

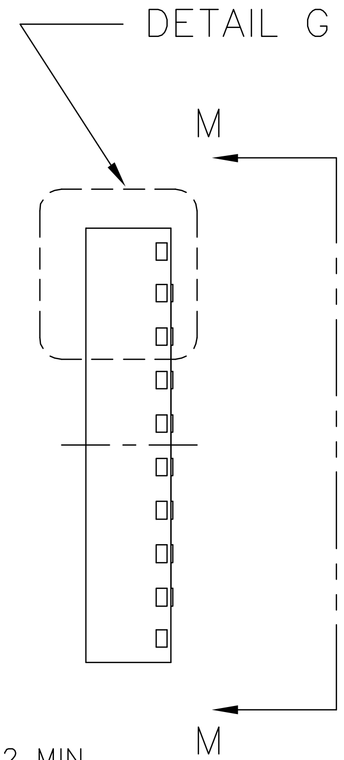

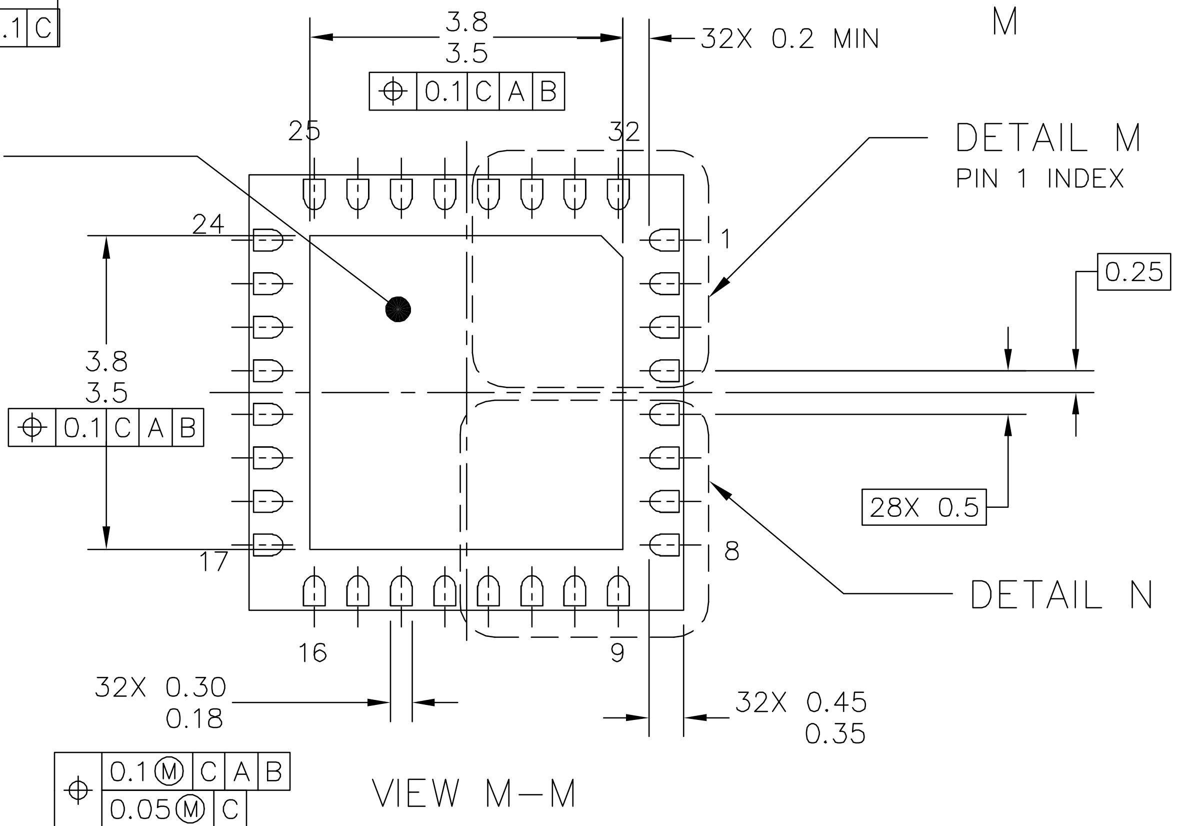

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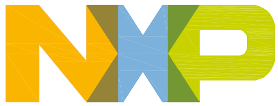
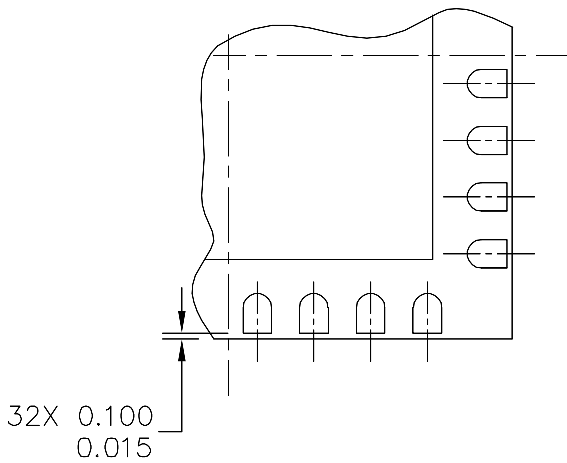
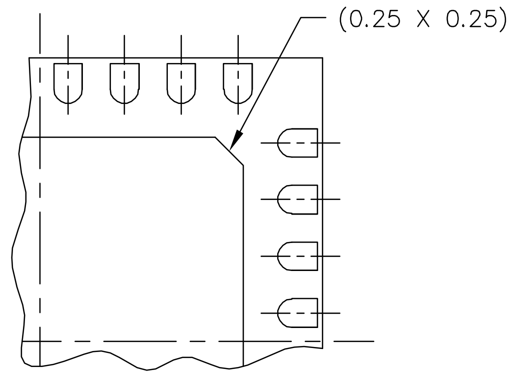
TITLE: THERMALLY ENHANCED QUAD FLAT NON—LEADED PACKAGE (QFN) 32 TERMINAL, 0.5 PITCH (5 X 5 X 1) 3.6 X 3.6 EP, CASE OUTLINE	DOCUMENT NO: 98ARE10566D REV: D	
	STANDARD: JEDEC MO—220 VHHD—4	
	SOT617—14 01 FEB 2016	

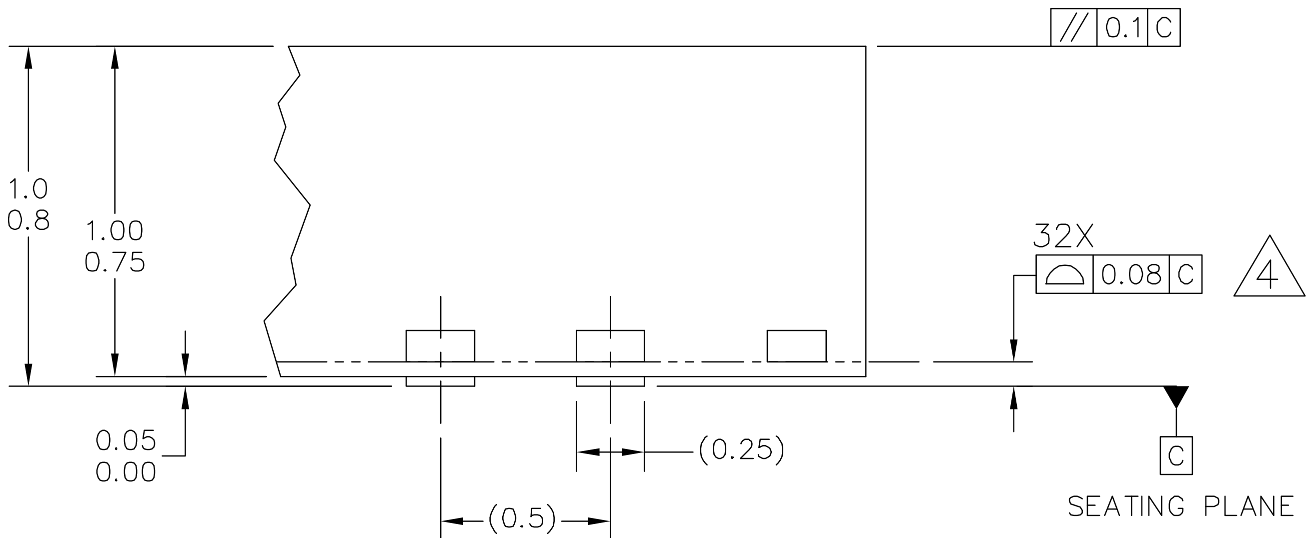






DETAIL N
PREFERRED CORNER CONFIGURATION

DETAIL M
PREFERRED BACKSIDE PIN 1 INDEX



DETAIL G
VIEW ROTATED 90° CW

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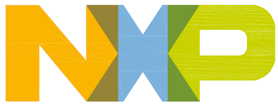
	STANDARD: JEDEC MO–220 VHHD–4
	SOT617–14 01 FEB 2016



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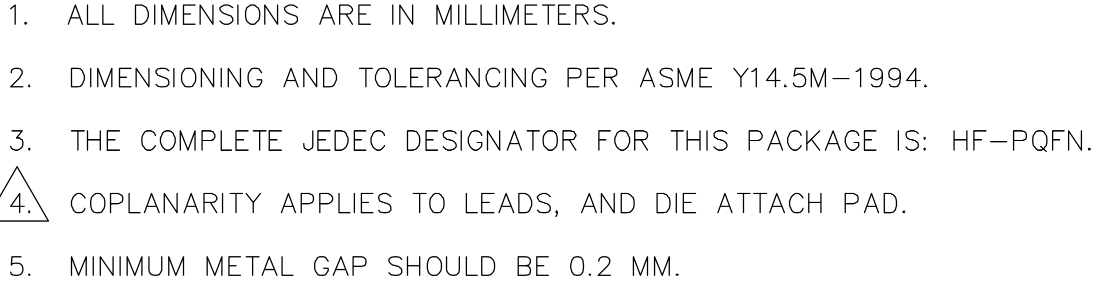

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4. (triangle) COPLANARITY APPLIES TO LEADS, AND DIE ATTACH PAD.
5. MINIMUM METAL GAP SHOULD BE 0.2 MM.

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